Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	55	CLEAN\$3 SAME IMAGE SAME SENSOR SAME PACKAGE	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 13:01
S2	74	("4710797" "4769344" "5037779" "5343076" "6194251" "6274927").PN. OR ("6384472"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 13:30
S3	31402	(substrate or wafer or semi\$1conductor or semiconductor) and clean\$3 and rotat\$3 and (spray\$3 or nozzle)	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 13:31
S4	14600	(substrate or wafer or semi\$1conductor or semiconductor) and clean\$3 and rotat\$3 and (spray\$3 or nozzle) and seal\$3	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 13:32
S5	861	(substrate or wafer or semi\$1conductor) same clean\$3 same rotat\$3 same (spray\$3 or nozzle) and seal\$3	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:23
S6	1123	134/153	US-PGPUB; USPAT; USOCR	OR	ON .	2006/08/03 15:24
S7	349	134/151	US-PGPUB; USPAT; USOCR	OR	ON :	2006/08/03 15:24
S8	497	134/137	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:24
S9	781	134/56R	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:25
S10	214	134/84	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:25
S11	142	134/85	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:25
S12	90	134/89	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:25
S13	4	S6 and (image near sens\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:25

S14	18593	yang.in.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:25
S15	5	(reg near yang)".in"	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/03 15:26
S16	60340	"34".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 13:47
S17	788	34/58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 17:01
S18	10	60/316,725	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 15:02
S20	186	34/576	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 17:01
S21	34	S20 and rotat\$3 and clean\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:24
S22	119	34/585	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:27
S23	9042	(wafer or substrate or semi\$1conductor or semiconductor) and horizontal same (spray\$3 or nozzle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:29
S24	5346	S23 and rotaț\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:28

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S25	2969	S24 and clean\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:28
S26	1093	(wafer or substrate or semi\$1conductor or semiconductor) same (horizontal same (spray\$3 or nozzle)) same rotat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:30
S27	411	(wafer or substrate or semi\$1conductor or semiconductor) same (horizontal near10 (spray\$3 or nozzle)) same rotat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:30
S28	278	(wafer or substrate or semi\$1conductor or semiconductor) near10 (horizontal near10 (spray\$3 or nozzle)) same rotat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:47
S29	42	(wafer or substrate or semi\$1conductor or semiconductor) same (lateral near5 (spray\$3 or nozzle)) same rotat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 18:50
S30	762	(wafer or substrate or semi\$1conductor or semiconductor) same (side near5 (spray\$3 or nozzle)) same rotat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 19:44
S31	6178	clean\$3 same rotat\$3 and ((spray or nozzle) near5 (wafer or substrate or semi\$1conductor or plate or chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 19:46
S32	2825	clean\$3 same rotat\$3 same ((spray or nozzle) near5 (wafer or substrate or semi\$1conductor or plate or chip))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 20:12
S33	674	(image adj sensor) same clean\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 20:12
S34	253	(image adj sensor) near10 clean\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/08/04 20:13

S35	237	(image adj sensor) near8 clean\$3	US-PGPUB;	OR	ON	2006/08/04 20:13
l			USPAT;			
			USOCR;			
	-		EPO; JPO;			
			DERWENT			